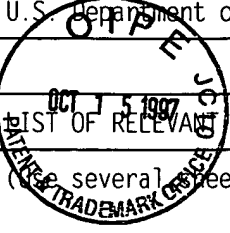


U.S. Department of Commerce, Patent and Trademark Office	Docket No.	Serial No.
	APPM/1931	08/856,116
 LIST OF RELEVANT ART CITED BY APPLICANT (Use several sheets if necessary)	Applicant	
	Liang-Yuh Chen, Fusen Chen, Moshe Eizenberg, and Roderick Craig Mosely	
	Filing Date	Group
	May 14, 1997	Unknown

U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
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	AD						
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Foreign Patent Documents

Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

BES	AN	K. Mikagi, H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa, "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film," 1996 IEEE, pp. 365-368
BES	AO	Y. Shacham-Diamand, V. Dubin and M. Angyal, "Electroless Copper Deposition for ULSI," 1995 Elsevier Science S.A., pp. 93-103
BES	AP	Electromigration and Diffusion in Pure Cu and Cu(Sn) Alloys, C.-K. Hu, K. L. Lee, D. Gupta, and P. Blauner, Mat. Res. Soc. Symp. Vol 427, (96-105)

Examiner <u>Bernard E. Souw</u>	Date Considered <u>07/02/99</u>
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Examiner

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